



SURFACE MOUNT DATALINE PROTECTION DEVICE

Features

- 300 Watts Peak Pulse Power (tp = 8x20µs)
- Transient Protection for Data Line to IEC61000-4-2 level 4 (ESD), 8kV HBM
 - Contact: Discharge ±30kV
 - Air: Discharge ±30kV
- IEC 61000-4-4 (EFT)
- Low Leakage Current
- Surface Mount Package Ideally Suited for Automated Insertion
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

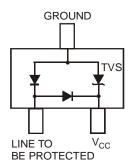
Mechanical Data

- Case: SOT323
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe) (63)
- Terminal Connections: See Diagram
- Weight: 0.006 grams (approximate)





Top View



Device Schematic

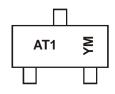
Ordering Information (Note 4)

Part Number	Case	Packaging
DLPT05W-7	SOT323	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



AT1 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: Z = 2012) M = Month (ex: 9 = September)

Date Code Key

Year	201	1	2012		2013	20	14	2015		2016	2	2017
Code	Υ		Z		Α	E	3	С		D		Е
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings $@T_A = 25^{\circ}C$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Pulse Power (tp = 8x20µs, per Figure 2)	P _{PK}	300	W
Peak Forward Voltage (I _{PP} = 1A, tp = 8x20µs, per Figure 2)	V_{FP}	2.1	V
Diode Peak Repetitive Reverse Voltage	V_{RRM}	75	V

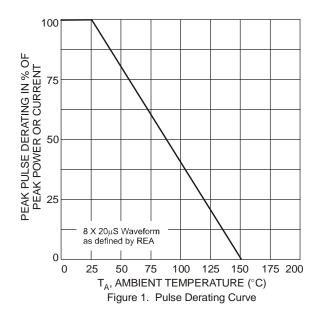
Thermal Characteristics

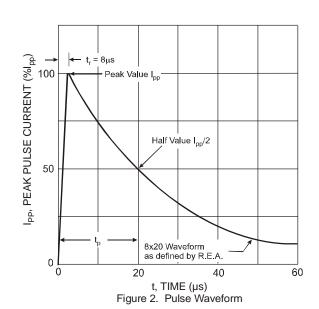
Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ hetaJA}$	625	°C/W
Operating and Storage Temperature Range	T_J , T_{STG}	-55 to +150	°C

Electrical Characteristics @TA = 25°C unless otherwise specified

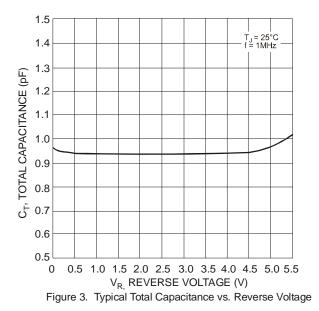
Reverse Standoff Voltage	Breakdown Voltage V _{BR} @ I _T		Test Current	Max. Reverse Leakage @ V _{RWM} (Note 6)	Max. Clamping Voltage @ I _{pp} = 1A (Notes 7 & 8)	Max. Peak Pulse Current (Notes 7 & 8)	Typical Total Capacitance (Note 9)
V _{RWM} (V)	Min (V)	Max (V)	I _T (mA)	I _R (μA)	V _C (V)	Ipp(A)	(pF)
5	6.0	_	1.0	20	9.8	17	1.9

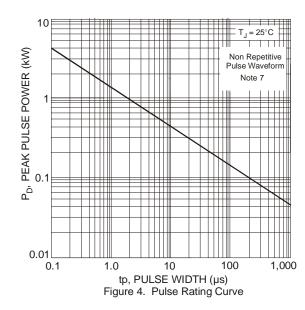
- 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.
- 6. Short duration pulse test used to minimize self-heating effect.
- 7. Clamping voltage value is based on an $8x20\mu s$ peak pulse current (I_{pp}) waveform.
- 8. Measured from line to be protected to ground pin. 9. $V_R = 0V$, f = 1MHz from line to be protected to ground pin.



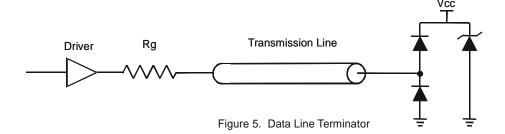








Typical Application Schematics



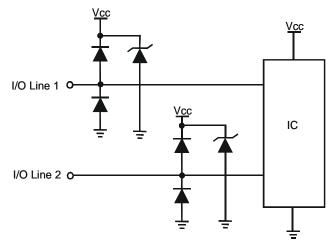
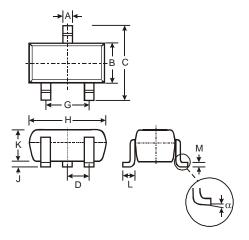


Figure 6. Data Line Protection

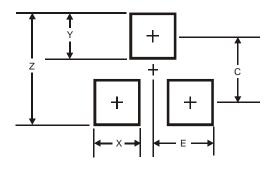


Package Outline Dimensions



SOT323							
Dim	Min	Min Max					
Α	0.25	0.40	0.30				
В	1.15	1.35	1.30				
С	2.00	2.20	2.10				
D	-	-	0.65				
G	1.20	1.40	1.30				
Н	1.80	2.20	2.15				
J	0.0	0.10	0.05				
K	0.90	1.00	1.00				
L	0.25	0.40	0.30				
M	0.10	0.18	0.11				
α	0°	8°	-				
All Dimensions in mm							

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.8
Х	0.7
Y	0.9
С	1.9
E	1.0



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